

Overview

HP Elite x3



- 1. Power LED
- 2. Status bar
- 3. Back arrow

- 4. Speaker
- 5. Earpiece and speaker
- 6. 8 MP camera

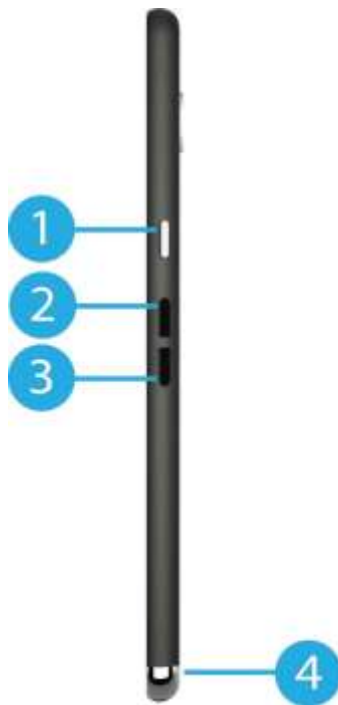
- 7. Iris camera
- 8. Search
- 9. Home key



- 1. 16 MP camera
- 2. Flash

- 3. Fingerprint reader
(Fingerprint reader will not be enabled until OTA update coming soon)
- 4. Pogo pins

Overview



1. Power button
2. Volume up

3. Volume down
4. Microphone



1. Nano SIM/micro SD Slot

Overview



1. 3.5mm combo headset/microphone jack



1. USB 3.0 Type-C™

Overview

At A Glance

- Built-for-business mobile device delivering seamless phablet, laptop and desktop business productivity in a single device
- Windows 10 Mobile
- Microsoft Continuum support
- Qualcomm® Snapdragon® 820 processor
- Indoor/outdoor, edge-to-edge display
 - 5.96" diagonal WQHD (2560 x 1440) AMOLED multitouch display
 - 494 PPI
 - Corning® Gorilla® Glass 4 and anti-smudge coating
- 4GB LPDDR4 memory
- 64GB internal storage
- Dual SIM Model; Single SIM Model
- Graphite/Chrome
- Passed MIL-STD 810G ¹
- Passed IP67 ²
- Front-facing audio speakers tuned by Bang & Olufsen and noise canceling omni-directional mics
- 16 MP rear camera. 8 MP front-facing camera for video conferencing, photos, and more
- Dual biometric authentication with Iris camera and finger print reader, with ultimate security measure enabled by Qualcomm and Windows platforms.
- Optional HP Elite x3 Desk Dock
- Optional HP Elite x3 Lap Dock is designed as an ultra-slim, near borderless 12.5" diagonal display notebook form factor that connects with the HP Elite x3 to achieve a seamless Windows Continuum computing experience
- Standard commercial 1 year limited warranty with extended service available with optional HP Care Packs

NOTE: See important legal disclosures for all listed specs in their respective features sections.

¹ MIL-STD 810G is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. MIL-STD 810G test results are not a guarantee of future performance under these test conditions. Damage under the MIL-STD 810G test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

² IP 67 tested. Test results are not a guarantee of future performance under these test conditions. Damage under the test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

Technical Specifications

PRODUCT NAME

HP Elite x3

OPERATING SYSTEM

Preinstalled Windows 10 Mobile*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 Mobile is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

NOTE: Includes Word Mobile, Excel Mobile, PowerPoint Mobile and OneNote.

PROCESSOR*

Qualcomm® Snapdragon 820 (2.15 GHz, 4 cores)*

* Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Qualcomm's numbering is not a measurement of clock speed.

CHIPSET

Qualcomm® MSM8996

GRAPHICS

Qualcomm® Adreno 530 GPU (integrated in Qualcomm® Snapdragon 820 processor)

DISPLAY

5.96" diagonal WQHD AMOLED multitouch display (2560 x 1440)*

Type	AMOLED multitouch display
Size	5.96" diagonal
Resolution	WQHD (2560 x 1440)*
Multitouch	Yes
Protection	Corning® Gorilla® Glass 4 and anti-smudge coating
Brightness	350 nits (Typical)
Pixels Per Inch	494 PPI

* WQHD content required to view WQHD images.

Technical Specifications

STORAGE AND DRIVES

Internal Storage*

64 GB eMMC 5.1

*For storage, GB = 1 billion bytes. Actual formatted capacity is less. Up to 8 GB is reserved for system recovery software.

Expansion Storage

(1) microSD - supporting expansion up to 2TB*

* MicroSD shares the same slot with second SIM on Dual SIM Model. MicroSD cards sold separately. Supports up to 2TB capacity when this capacity becomes available.

MEMORY

4 GB LPDDR4 SDRAM (onboard)*

PORTS/SLOTS

Ports

1 USB 3.0 Type-C™

1 3.5 mm 3 and 4 pole headphone jack

Video out via USB 3.0 DP alt mode

Pogo pins

Slots

Configuration Options:

Dual SIM Model

Dual Nano SIM

or Nano SIM + microSD card

Single SIM Model*

Nano SIM + microSD card

*Single SIM Model may not be available in some countries.

NETWORKING/COMMUNICATIONS

WWAN: 2G/3G/4G, LTE-A with carrier aggregation ¹

- Supports up to CAT6

Wireless LAN (WLAN) ²

802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.0 LE combo; Miracast supported ³

Other: NFC (NQ210); Wireless Charging (Qi/PMA); Standalone and Assisted GPS

Technical Specifications

1 GSM only. WWAN requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

2 For all 802.11 wireless, wireless access point and Internet service is required and is not included. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

3 Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>.

AUDIO/MULTIMEDIA

Audio

- 2 front-facing stereo speakers (one with earpiece)
- 3 integrated omni-directional microphones with Qualcomm Fluce™ Pro technology
- 1 external microphone (from headset jack)
- Snapdragon Audio+ support
- Audio by B&O PLAY

Camera – Front

- 8MP Front Facing Camera
 - 2x2 Binning for high quality FHD video conferencing
 - Record at FHD/30fps
 - Low light capabilities
 - 5P Japanese Lens f/2.2
 - 1.12um pixels – 16:9 Native Format – 3872x2192

Camera – Back

- 16MP Rear Facing Camera
 - Record 4K/30fps or FHD/30fps
 - Low light capabilities
 - 6P Japanese Lens f/2.2
 - High output, ultra-high CRI LED flash
 - PDAF (phase detection auto focus)
 - Large 1.31um pixels – 4:3 Native Format – 4608x3456

SOFTWARE AND SECURITY

Preinstalled Software with Windows 10 Mobile Operating System

HP Value Add Software

- HP Workspace*
- HP All-in-One Remote
- HP Device Hub
- 12C calculator

Technical Specifications

* HP Workspace subscription required. Corporate applications must be licensed on corporate network for virtualization. Requires the HP Elite x3 to be docked with the HP Elite x3 Desk Dock or connected to the HP Elite x3 Lap Dock, each sold separately or as part of a solution bundle.

3rd Party

Salesforce universal app^{1,2}

Winzip Universal

Microsoft Products

Word Mobile

Excel Mobile

PowerPoint Mobile

OneNote

OneDrive

Microsoft Edge

Continuum²

Skype³

Groove music

Cortana⁴

Remote Desktop

Manageability

AirWatch (via MDM settings)⁵

MobileIron(via MDM settings)⁵

HP Touchpoint Manager (via MDM settings)⁵

Client Security Software

VPN profile setup from settings menu⁵

1 Salesforce subscription required. The preinstalled Salesforce app is a link to its web-based version..

2 For multi-screen Continuum experience, one of the following accessories are required: 1) Desk Dock using USB-C™ to DisplayPort connection to external display, 2) Lap Dock using USB-C™ connection to Lap Dock's integrated display, 3) Dongle using USB-C™ to DisplayPort, HDMI or VGA connection to external display, 4) Miracast-enabled external display or Miracast dongle attached to an external display. All docks and dongles sold separately.

3 Skype is not offered in China.

4 Check link below for Cortana availability:

<http://windows.microsoft.com/en-us/windows-10/cortanas-regions-and-languages#v1h=tab01>

5 Will need to be configured by user/IT manager.

Security Features (Standard)

- Dual biometrics with Iris recognition and Fingerprint reader
- FIPS 140-2 cryptography
- Qualcomm® processor includes Secure Boot, 128-bit key Unified Image Encryption, 256-bit key Full Disk Encryption, Anti roll back and fTPM 2.0 security
- Windows 10 Mobile includes 128 key Bitlocker encryption and Enterprise grade VPN

Technical Specifications

POWER

Power Supply

10 W 5V/2A adapter

Battery

4150 mAh Li-ion polymer

Battery Life

Standby up to 500 hours*

Talk up to 33 hours*

Web up to 14 hours*

*Actual battery times will vary depending on the network conditions, settings, configuration, individual usage pattern and other conditions. Use of wireless and backlight will significantly decrease battery run time. Maximum capacity will naturally decrease with time and usage.

Video Playback up to 13 hours*

*Tested by HP using 720p (1280x720), video media file, single SIM, 200 nits brightness, airplane mode on, volume level at 50% with wired headset inserted. Actual battery life will vary depending on configuration and maximum capacity will naturally decrease with time and usage.

WEIGHTS & DIMENSIONS

Weight*

Starting at 194 g (0.4277 lb)

Weight will vary by configuration.

Dimensions - (portrait orientation)*

83.5 x 161.8 x 7.8 mm (3.29 x 6.36 x 0.31 in)

SENSORS

ALS (Ambient Light Sensor) + Proximity Combo

Accelerometer + Gyro

Pressure

Hall Effect

NFC (NQ210)

Standalone and Assisted GPS

eCompass

Technical Specifications

COLOR

Graphite/Chrome

TESTING

Passed IP 67, providing seals against liquid and dust ingress to IP 67 rating.*

Passed MIL-STD 810G testing.**

*IP 67 tested. Test results are not a guarantee of future performance under these test conditions. Damage under the test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

**MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

WHAT'S IN THE BOX?

HP Elite x3, 10W power adapter, USB Type-C™ to USB Type A cable, documentation*

*Varies by configuration bundle.

SERVICE AND SUPPORT

HP Services offers a 1-year limited warranty. Internal batteries have the same 1-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	5 V (9V max)
	Average Operating Power	1.2 W
	Max Operating Power	< 15 W
Temperature	Operating	14° to 131° F (-10° to 55° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Random Vibration	
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)

Technical Specifications

NETWORKING/COMMUNICATIONS

HP Elite x3 is a high end mobile device based on Qualcomm® Snapdragon 820 processor. It supports the following wireless technologies and protocols.

WWAN*

Technology/Operating bands

WCDMA/HSDPA/HSUPA/HSPA+: 2100(Band I), 1900 (Band II), AWS(Band IV), 850 (Band V), 900 (Band VIII) MHz

GSM/GPRS/EDGE: 1900 MHz (Band II), 1800 MHz (Band III), 850 MHz (Band V), 900 MHz (Band VIII) MHz

EMEA+APJ model

- 2G: 850/900/1800/1900MHz
- 3G: B5/8/2/1/4
- 4G: FDD B1/3/5/7/8/19/20/26/28, TDD B38/39/40/41(roaming bands B2/4/12/17/29)
- 2DL CA: B3+B20, B3+B7, B20+B7, B7+B28, B1+B3, B3+B5, B3+B8, B3+B19,B3+B26, B1+B5, B1+B19, B1+B26, B3+B28, B1+B41, TDD Intra CA

LTE:

FDD 2000(B1), 1800 (B3), 850 (B5), 2600 (B7), 900(B8), 800U (B19), 800DD (B20), 850+(B26), 700APT(B28); TDD 2600 (B38), 1900+(B39), 2300 (B40), 2500 (B41)
2DL CA -- B3+B20, B3+B7, B20+B7, B7+B28, B1+B3, B3+B5, B3+B8, B3+B19,B3+B26, B1+B5, B1+B19, B1+B26, B3+B28, B1+B41, TDD Intra CA

No CDMA 1X & EVDO, No TD-SCDMA

Americas model

- 2G: 850/900/1800/1900MHz
- 3G: B5/8/2/1/4
- 4G: FDD B2/4/5/7/12/17/29/30 (roaming bands B1/3/20)
- 2DL CA: B2+B29, B4+B29, B2+B17, B4+B17, B2+B12, B4+B12, B4+B7

LTE:

1900 (B2), AWS (B4), 850 (B5), 2600 (B7), 700A (B12), 700B (B17), 700D(B29), 2300 (B30)
2DL CA -- B2+B29, B4+B29, B2+B17, B4+B17, B2+B12, B4+B12, B4+B7

No CDMA 1X & EVDO, No TD-SCDMA

Americas model connected by Verizon (US only)

Main Bands:

CDMA 1X & EVDO: 800MHz(BC0), 1900MHz(BC1)

LTE: FDD1900 (B2), AWS (B4), 850 (B5), 700c (B13)

2DL CA: B4+B13, B2+B13, B4+B4, B2+B2, B2+B5, B4+B5

Other Bands for Roaming:

GSM/GPRS/EDGE: 1900 MHz (Band II), 1800 MHz (Band III), 850 MHz (Band V), 900 MHz (Band VIII) MHz

WCDMA/HSDPA/HSUPA/HSPA+: 2100(Band I), 1900 (Band II), AWS(Band IV), 850 (Band V), 900 (Band VIII) MHz

LTE: 1800 (B3), 2600 (B7), 800DD (B20), 700APT(B28A)

No SVLTE, No TD-SCDMA

Technical Specifications

Wireless protocol standards	CDMA: CDMA2000 1X & EVDO GSM/GPRS/EDGE: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9. UMTS/WCDMA/HSPA+: Release 99 and Release 8 LTE CAT6 Advanced Receiver Type 3i
Maximum Data Rates:	CDMA2000 1X: 144Kbps CDMA2000 1X EVDO Rev A: UL 1.8Mbps / DL 3.1Mbps HSPA+: UL 5.76 Mbps / DL 21.6 Mbps HSPA: UL 5.76 Mbps / DL 7.2 Mbps WCDMA PS: UL 384 kbps / DL 384 kbps WCDMA CS: UL 64 kbps / DL 64 kbps GPRS: UL 85.6 kbps / DL 107 kbps EDGE: UL 236.8 kbps / DL 296 kbps LTE CAT 6: UL 50Mbps / 300Mbps
Maximum output power	HP Elite x3 follows 3GPP definitions for each technology and standard. Actual data rate will vary due to the location, environment, network conditions, available bands, and other factors. CDMA 1X & EVDO: 24 dBm WCDMA/HSPA/HSPA+ : 24 dBm GPRS 1900/1800 MHz: 30 dBm GPRS 900/850 MHz: 33 dBm EDGE 1900/1800 MHz: 26 dBm EDGE 900/850 MHz: 27 dBm LTE: 23dBm
Connectivity	Supporting WLAN 802.11 a/b/g/n/ac dual bands; 2x2 MIMO for 11ac; Supporting Miracast/Wi-Fi Direct mirroring. Supporting Bluetooth Class 2, Bluetooth 4.0 LE and security
GPS	Standalone, A-GPS, GLONASS, Beidou
GPS Bands:	GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1593-1610MHz; Beidou 1561.098MHz/1589.742MHz
NFC	Supporting peer to peer and R/W modes for type A, B, and F standards and tags type 1, 2, 3, and 4.
Wireless Charging	HP Elite x3 implements with WPC(Qi)/PMA dual mode wireless charging feature; supporting 5W and foreign object detection for Qi v1.1 and PMA compliance.

* WWAN requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

Technical Specifications

POWER

HP Single-cell Polymer Battery (15.98 WHr)

Cells/Type	1-cell Lithium-Ion Polymer
Amp-hour capacity	4150 mAh
Watt-hour capacity	15.98 WHr
Battery recharge time	System in OFF or Standby Mode <3 hours

MIL-STD 810G TEST

Drop*	The drop test was performed in accordance with MIL-STD-810G, Method 516.6, Procedure IV. The objective of this test was to determine whether the unit was operational after being dropped from desk height. For this test, 26 drops were performed from 4 ft onto every side, angle and edge onto 2" of plywood over steel over concrete.
High Temperature test*	The High Temperature test was performed in accordance with MIL-STD-810G, Method 501.5, Procedure I (Storage). This test evaluated the units' performance while it was being exposed to high temperature conditions: 71°C (160°F) nonoperational. Test cycle 24 hours; test consisted of seven cycles.
High Temperature test*	The High Temperature test was performed in accordance with MIL-STD-810G, Method 501.5, Procedure II (Operation). This test evaluated the units' performance while it was being exposed to high temperature conditions: 60°C (140°F) operational. Four hours duration.
Low Temperature test*	The Low Temperature test was performed in accordance with MIL-STD-810G, Method 502.5, Procedure I (Storage). This test evaluated the unit's performance while it was being exposed to low temperature conditions: -51°C (-60°F) nonoperational. Four hours duration.
Low Temperature test*	The Low Temperature test was performed in accordance with MIL-STD-810G, Method 502.5, Procedure II (Operation). This test evaluated the unit's performance while it was being exposed to low temperature conditions: -29°C (20°F) operational. Four hour duration.
Thermal Shock test*	The Thermal Shock test was performed in accordance with MILSTD-810G, Method 503.5, Procedure I. The objective of this test was to determine whether the unit could be safely operated after being exposed to sudden changes in ambient temperature while non-operational. The high temperature was set to be 96°C (205°F) and the low temperature to be -51°C (-60°F); three high-to-low cycles were performed.
Altitude*	The Altitude test was performed in accordance with MIL-STD-810G, Method 500.5, Procedure I (Storage) and II (Operation). The altitude level simulated for both procedures was 15,000 feet at 57kPa. Four hour duration.
Humidity*	The humidity test was performed in accordance with MIL-STD-810G, Method 507.5, Procedure II. Relative humidity 95%. Temperature cycled between 86oF and 140oF. Test cycle 24 hours; test consisted of ten cycles.
Dust*	The dust test was performed in accordance with MIL-STD-810G, Method 510.5, Procedure I. Test parameters were set so that the unit was dusted with Arizona Road Dust for six hours while being operated. Each cycle was one day (24 hours); ten cycles with the temperature being cycled between 30°C (86°F) and 60°C (140°F); and relative humidity was a constant 95%.

Technical Specifications

Vibration*	The vibration test was performed in accordance with MIL-STD-810G, Method 514.6, Procedure I category 4. This test evaluated the units performance after it has been subjected to higher levels of vibration while in storage: Operational U.S. highway truck exposure, 1000 mile Simulation and One hour/axis duration.
Vibration 2*	The vibration test was performed in accordance with MIL-STD-810G, Method 514.6, Procedure I category 24. This test evaluated the units performance after it has been subjected to higher levels of vibration while in storage: Non-operational 0.04 g ² /Hz at 20-1000 Hz, -6 dB/octave at 1000-2000 Hz and One hour/axis duration.
Shock*	The shock test was performed in accordance with IL-STD-810G, Method 516.6, Procedure I. This test objective was to determine whether the unit could be safely operated after being exposed to sudden physical shock events while operational. For this test, 3 shocks were performed across each axis and direction for a total of 18 shocks -40Gs peak, 11ms.
Freeze/Thaw test*	The Freeze/Thaw test was performed in accordance with MILSTD-810G, Method 524.54 Procedure III. The objective of this test was to determine whether the unit could be safely operated after being exposed to a temperature drop of -10°C (14°F) for two hours. Unit is removed and checked for operation.
Sand test*	The Sand test was performed in accordance with MIL-STD-810G, Method 510.5 Procedure II
Explosive Atmosphere*	The Explosive Atmosphere test was performed in accordance with MIL-STD 810G, Method 511.5 Procedure I.

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Technical Specifications

COUNTRY OF ORIGIN

China

Technical Specifications

PRODUCT AVAILABILITY BY REGION

Region	Country/Area	Region	Country/Area
AMS	Canada	EMEA	Austria
	Chile		Belarus
	Colombia		Belgium
	El Salvador		Bulgaria
	Guatemala		Croatia
	Honduras		Czech Republic
	Jamaica		Ethiopia
	Mexico		Finland
	US		France
	Ecuador		Germany
	Peru		Greece
	Panama		Hungary
	Puerto Rico		Ireland
	Costa Rica		Italy
	Paraguay		Kazakhstan
	Cayman Island		Luxembourg
Suriname	Netherlands		
Trinidad	Denmark		
APJ	Australia		Norway
	New Zealand		Serbia
	Malaysia		Slovakia
	Philippines		Slovenia
	Singapore		Sweden
	Thailand		Poland
	Taiwan		Portugal
	Hong Kong		Qatar
	Japan		Romania
			Russia
	Saudi Arabia		
	South Africa		
	Spain		
	Switzerland		
	Turkey		
	United Arab Emirates		
	United Kingdom		

Options and Accessories (sold separately and availability may vary by country)

<u>Type</u>	<u>Description</u>	<u>Part number</u>
<i>Docking</i>	HP Elite x3 Lap Dock	Y4T08AA
	HP Elite x3 Desk Dock	V5H01AA
	HP Elite USB-C Dock	Z9R42AA
<i>Cases</i>	HP Elite x3 Rugged Case	V8Z63AA
	HP Elite x3 Silicone Case	V8Z62AA
	HP Elite x3 Wallet Folio Leather Case	V8Z61AA
<i>Screen Protectors</i>	HP Elite x3 Anti-Fingerprint Screen Protector (3-pack)	W8W95AA
	HP Elite x3 Anti-Shatter Glass Screen Protector (1-pack)	W8W94AA
	HP Elite x3 Privacy Screen (1-pack)	W8W96AA
<i>Adapters</i>	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to USB-A Adapter	N2Z63AA
	HP 45W USB-C Auto Adapter	Z3Q87AA
<i>Power/Charging</i>	HP Elite x3 Wireless Charger	W9A82AA
	HP 12W USB Auto Power Adapter	G4H12AA
	HP 15W USB-C AC Adapter	N4G74AA
<i>Multimedia</i>	HP UC Wireless Duo Headset	W3K09AA
	HP UC Wireless Mono Headset	W3K08AA
<i>Others</i>	HP Tablet Cleaning Kit	K6F99AA
	HP USB-C Travel Hub	Z9G82AA

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